

Lynx™ Product Family

Lynx Routing Guide

February 2019

Dave Spencer

Product Marketing Manager

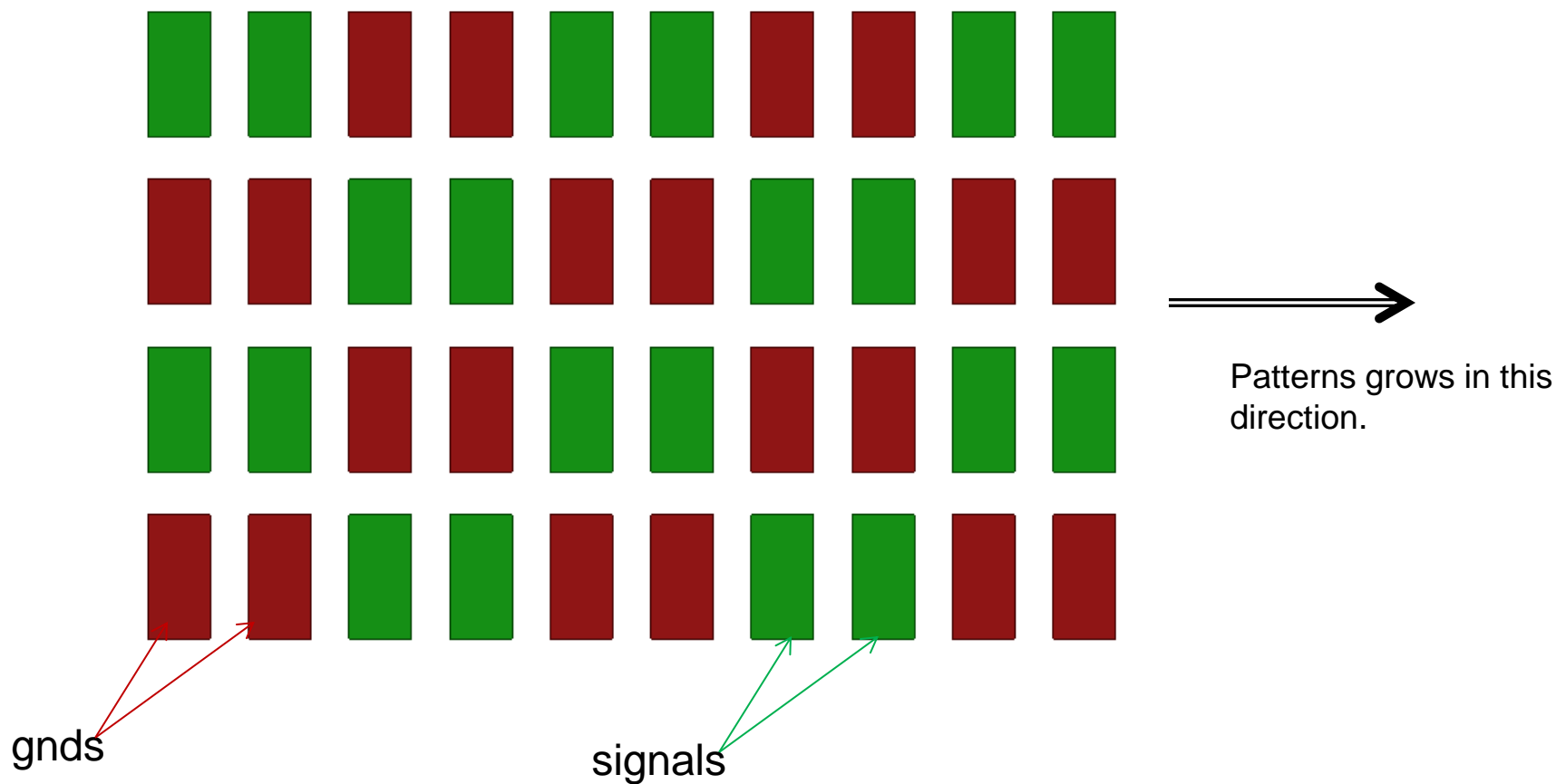
Amphenol Information Communications
and Commercial Products

MeZanine
Products

Amphenol ICC

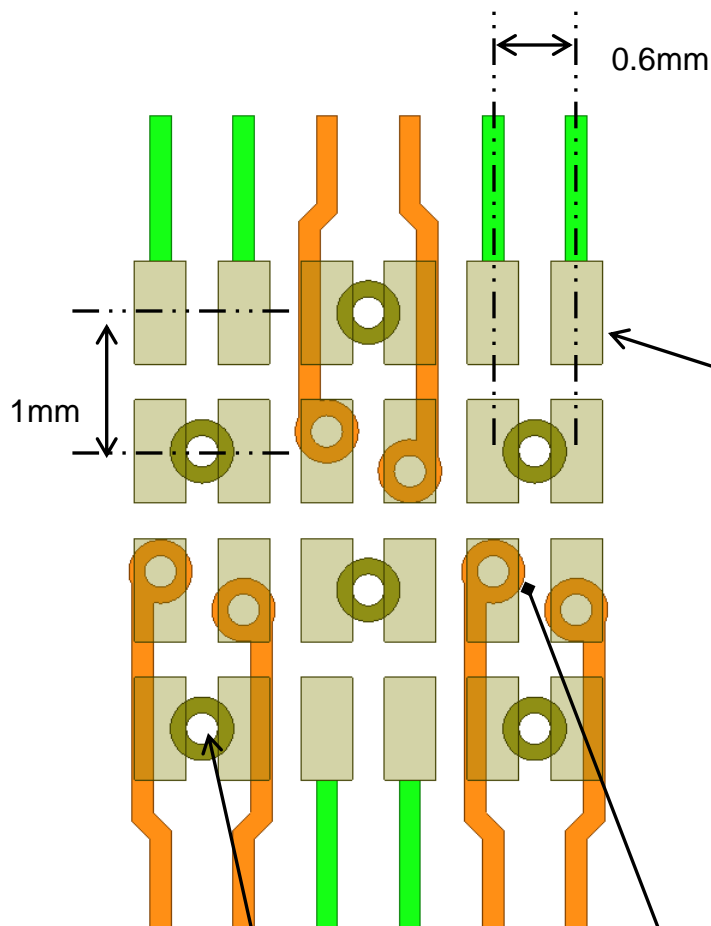
Standard Lynx Footprint

Signal and Ground layout



Standard Lynx Routing

Signal Vias and Layers



Lynx breakout can be achieved with 2 routing layers.

Green: top layer
Orange: inner layers

Solder Pad:
0.74 x 0.37 mm

Vias:
0.009-in dia
0.018-in pad

Trace width: 0.006-in

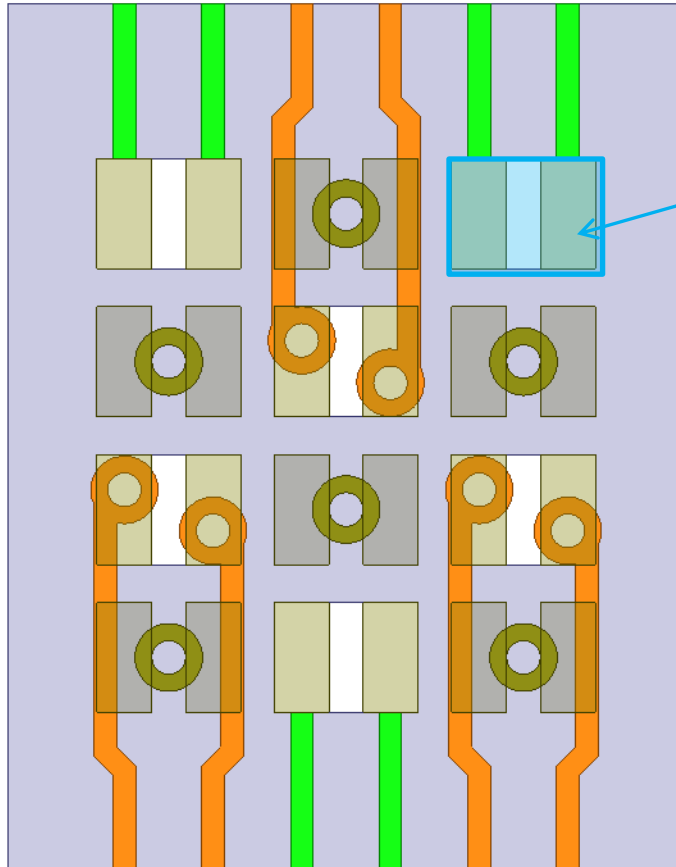
Min Cu – Cu clearance is 0.008-in.

GND via is shared between pads

Offset signal via pairs;
0.008-in pad to pad clearance

Standard Lynx Plane Layers

Anti-pad view



Ground plane anti-pads help to offset the capacitance of the surface pads.

Approx: 0.74 x 0.97mm

Questions?

Contact your local AICC Sales Representative, FAE, or:

Dave Spencer

Product Marketing Manager | Mezzanine Products

T: 717.915.1446

E: dspencer@interconsystems.com

Visit our website at: <https://www.amphenol-icc.com/mezzanine>